AMENDMENT TO THE CLAIMS

1. (Previously presented) A hot melt adhesive composition comprising:

a) about 10% by weight to about 50% by weight of at least one substantially aliphatic tackifying resin having a glass transition temperature of greater than 65°C;

b) about 20% by weight to about 60% by weight of at least one thermoplastic base polymer; and

c) 0% by weight to about 40% by weight of at least one wax;

wherein said tackifying resin concentration is less than said thermoplastic base polymer concentration.

2. (Original) The adhesive composition of Claim 1 wherein said thermoplastic polymer is selected from the group consisting of copolymers and terpolymers of ethylene; amorphous polyalphaolefins; rubbery block copolymers; homogeneous ethylene/α-olefin interpolymers and mixtures thereof.

3. (Original) The adhesive of Claim 1 wherein said composition comprises from about 15% by weight to about 40% by weight of said tackifying resin.

4. (Previously presented) The adhesive composition of Claim 1 wherein said tackifying resin has a melting point of greater than 140°C.

5. (Original) The adhesive of Claim 1 wherein said tackifying resin has a T_g of greater than about 68°C (about 155°F) at onset.

6. (Original) The adhesive of Claim 1 wherein said tackifying resin has a T_g of greater than about 70°C at onset.

7. (Original) The adhesive of Claim 1 wherein the tackifying resin has a Gardner Color of less than 3.

8. (Original) The adhesive of Claim 1 wherein the tackifying resin has a Gardner Color of from about 1 to about 2.

9. (Original) The adhesive of Claim 1 wherein said tackifying resin has a bromine value of less than about 5.

10. (Original) The adhesive of Claim 1 wherein the tackifying resin has less than about 10% by weight aromatics.

11. (Original) The adhesive of Claim 1 wherein the tackifying resin has less than about 5% by weight aromatics.

12. (Original) The adhesive of Claim 1 comprising from about 10% by weight to about 40% by weight of at least one wax.

13. (Original) The adhesive of Claim 1 wherein the wax is selected from the group consisting of synthetic waxes having a melting point of greater than about 80°C, microcrystalline waxes and paraffin waxes.

14. (Previously presented) The adhesive of claim 1 wherein said at least one thermoplastic base polymer is a copolymer of ethylene, at least one comonomer of said copolymer being selected from the group consisting of vinyl acetate, n-butyl acrylate, methyl acrylate, vinyl esters and mixtures thereof.

15. (Original) The adhesive of Claim 12 wherein said peel value is greater than about 140°F (about 60°C).

16. (Original) The adhesive of Claim 1 wherein said peel value is greater than about 65°C.

17. (Original) The adhesive of Claim 2 wherein said thermoplastic polymer is a homogenous ethylene/α-olefin interpolymer.

18. (Original) The adhesive of Claim 17 further comprising a block copolymer.

19. (Original) The adhesive of Claim 18 wherein the peel values are greater than about 70°C.

20. (Previously presented) A hot melt adhesive composition comprising:

a) about 10% by weight to about 50% by weight of at least one tackifying resin having a glass transition temperature of at least 65°C;

b) about 20% by weight to about 60% by weight of at least one thermoplastic base polymer selected from the group consisting of copolymers and terpolymers of ethylene; amorphous polyalphaolefins, homogenous ethylene/α-olefin interpolymer, and mixtures thereof; and

c) 0% by weight to about 40% by weight of at least one wax;

wherein said tackifying resin concentration is less than said thermoplastic base polymer concentration.

21. (Original) The composition of Claim 20 wherein said composition comprises from about 10% by weight to about 45% by weight of said tackifying resin.

22. (Currently amended) A hot melt adhesive composition comprising:

a) about 10% by weight to about 50% by weight of at least one hydrocarbon tackifying resin derived, at least in part, from dicyclopentadiene and having a glass transition temperature of greater than about 65°C;

b) about 10% by weight to about 80% by weight of at least one thermoplastic base polymer selected from the group consisting of copolymers and terpolymers of ethylene; amorphous polyalphaolefins, homogenous ethylene/α-olefin interpolymer, and mixtures thereof,[[; and]]

23. (Original) The adhesive of Claim 22 wherein said tackifying resin has a T_g of greater than about 68°C (about 155°F).

24. (Original) The adhesive of Claim 22 wherein greater than about 80 wt-% of the total resin unit is derived from dicyclopentadiene.

25. (Original) The adhesive of Claim 22 wherein the tackifying resin is hydrogenated.

26. (Original) The adhesive of Claim 22 further comprising up to about 40% by weight of a solid benzoate plasticizer.

27. (Original) The adhesive of Claim 22 wherein the peel values are greater than about 70°C.

28. (Previously presented) A hot melt adhesive comprising:

a) from about 10% by weight to about 80% by weight of at least one aliphatic tackifying resin having a glass transition temperature (T_g) of greater than 65°C; and

b) from about 10% by weight to about 80% by weight of at least one thermoplastic base polymer selected from the group consisting of copolymers and terpolymers of ethylene; amorphous polyalphaolefins, homogenous ethylene/α-olefin interpolymer, and mixtures thereof.

29. (Original) The adhesive composition of Claim 1 wherein the thermoplastic polymer is present in an amount ranging from about 20% by weight to about 50% by weight.

30. (Previously presented) A hot melt adhesive composition comprising:

a) about 10% by weight to about 50% by weight of at least one substantially aliphatic tackifying resin having a softening point of greater than 140°C;

b) about 20% by weight to about 60% by weight of at least one thermoplastic base polymer; and

c) 0% by weight to about 40% by weight of at least one wax;

wherein said tackifying resin concentration is less than said thermoplastic base polymer concentration.